

Backside Wafer Laser Grooving

WB-300FGS

The WB-300FGS is an advanced grooving solution for the backside metal of wafer prior to blade saw dicing. This metal grooving innovation enhances the dicing process by optimizing operational costs, extending the lifespan of blade saws, and elevating dicing quality. Notably, its integrated dust collection system eliminates the need for coating, ensuring a particle-free outcome throughout the entire process.

Feature



Quality enhancement solution before saw dicing

- No metal peeling solution and save blade lifespan

Galvo laser design for elevated throughput

- Max. speed 5 mm/s

No residues left and coating requirement

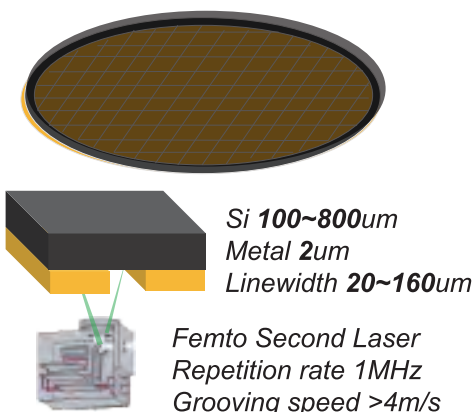
- Dust collector to eliminate all particles

Flat and outstanding sidewall performance

- Excellent depth & linewidth control

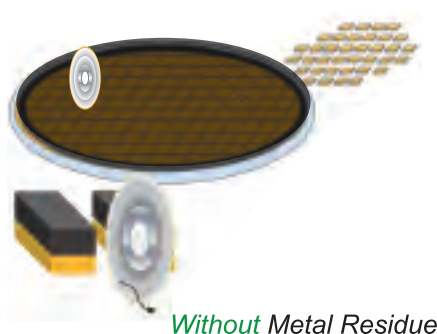
E&R Solution

Backside Laser Grooving



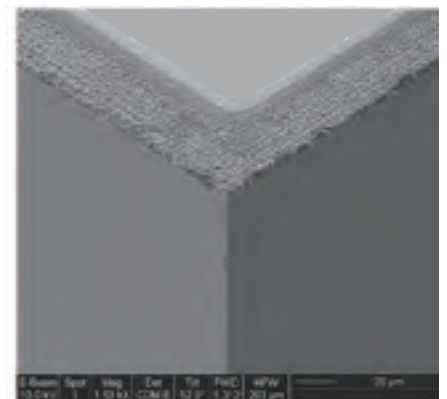
No particle remain
No coating require

Topside Blade Saw



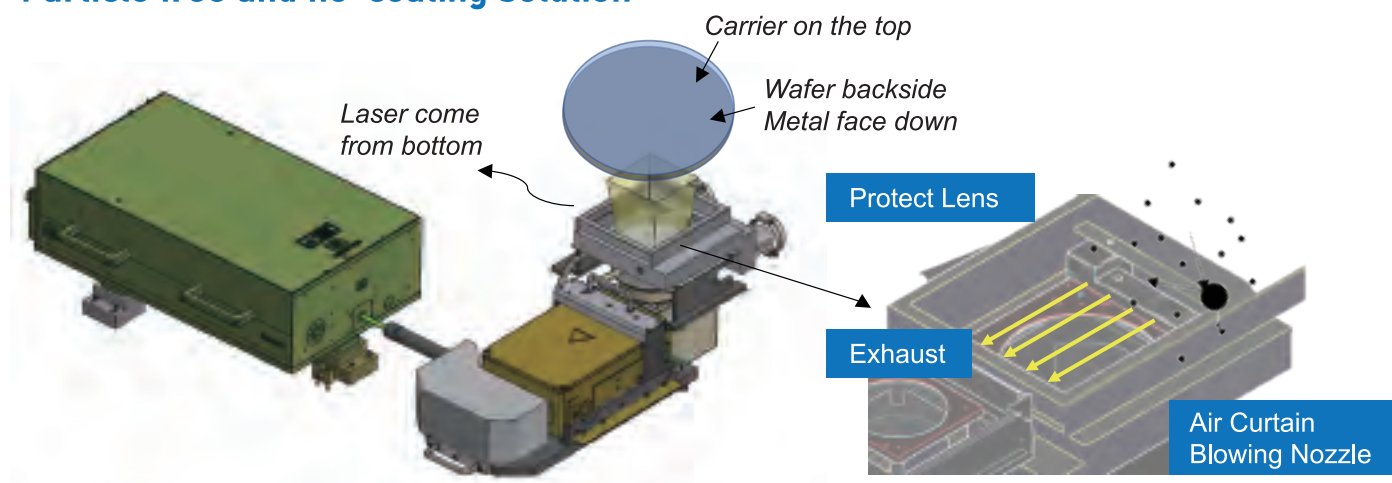
No damage Blade lifetime
Better CoO
No Metal residue remain
No Metal peeling

No Backside Metal Peeling



Dust Collection System

▪ Particle free and no-coating solution



Specification

WB Series		WB Series	
Process direction	Backside	Machine accuracy	±20um
Laser Source	Pico UV 355nm Femto Green 517nm Femto UV 355nm	X-Y Table Accuracy	±5um
Machine dimensions (WxDxH)	1900x2406x1936 mm	Spot size	15~30um
Workpiece size	φ 200&300	Safety Certification	SEMI S2/S8, S23, F47, NFPA 79, FDA
Wafer form	Bare wafer & FSC	Automation	SECS/GEM E5, E30, E37, E87, E90, E94, E142

Grooving Result

